



Final Product Change Notification

201603018F01

Issue Date: 13-Jun-2016

Effective Date: 25-Sep-2016

Dear

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online



QUALITY

Change Category

<input checked="" type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input checked="" type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage

Release of 8 inch wafer diameter for bidirectional ESD protection diodes

Details of this Change

Release of production using 8 inch wafer diameter for bidirectional ESD protection diodes in SOD323 (SC-76), SOD523 (SC-79) and SOT23 packages. In addition the thickness of the top metallization of the affected protection diodes will be adapted.

Old products: Production using 6 inch wafer diameter, top side metallization thickness 1.65µm

Changed products: Production using 6 and 8 inch wafer diameter, top side metallization thickness 1.75µm for 8 inch wafers

Production on 8 inch wafer diameter implies the use of the respective 8 inch wafer process technology.

Why do we Implement this Change

To increase flexibility and volume ramp-up.

Identification of Affected Products

The 8 inch products can be identified by a marker on the die surface.

Product Availability

Sample Information

Samples are available upon request

Latest sample request date for PCN samples is 15-July-2016

Production

Planned first shipment 26-Sep-2016

Impact

No impact to the products' functionality anticipated.

Disposition of Old Products

Supply using 6 inch wafer will be continued.

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 13-Jul-2016.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name GA Customer Support

e-mail address DiscrQA.Helpdesk.GA-Products@nxp.com

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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NXP Semiconductors

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Part Numbers Affected

PESD5V0S1BA,115

PESD5V0S1BA,115

PESD5V0S2BT,215

PESD5V0S1BB,115

PESD5V0S2BT,215

PESD5V0S1BB,115